



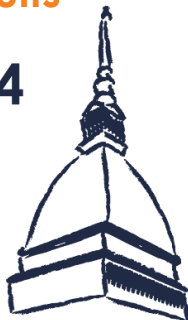
## The 14<sup>th</sup> International Workshop on the Electromagnetic Compatibility of Integrated Circuits

### EMC COMPO 2024

October 7<sup>th</sup>-9<sup>th</sup>, 2024

Politecnico di Torino

Torino, Italy



# CALL FOR PAPER

### ORGANIZATION AND VENUE

Welcome back to the land of Technology and Culture! After a successful EMC COMPO 2007, the EMC Community will gather again in Torino, Italy, from October 7<sup>th</sup> to 9<sup>th</sup>, 2024, to exchange views on research progress and technological developments in the various topics described hereunder.

The 14<sup>th</sup> International Workshop on the Electromagnetic Compatibility of Integrated Circuits, EMC COMPO 24 is co-sponsored by the IEEE EMC Society (EMCS).

### AIMS OF THE WORKSHOP

Aiming at exchanging experience among fellow professionals and academics, and bearing in mind the role of electronic components in terms of electromagnetic compatibility, safety and reliability of electronic modules and systems, EMC COMPO 2024 is the right place to achieve this goal. EMC COMPO will provide the opportunity to discuss hot topics through oral, poster sessions and tutorials.

### INFORMATION FOR AUTHORS

Authors are invited to submit original contributions in two-column and either one-page format for abstract submission (in proceedings only) or full-length (2–4 pages) format for paper submission (for IEEE Xplore Publication) through the online [EDAS submission system](#). The paper must follow the IEEE two-column A4 format for Conference Proceedings.

Authors of the best ranked accepted papers will have the opportunity to submit an **extended version** of their work in a special issue of the **IEEE Letters on Electromagnetic Compatibility Practice and Applications (L-EMCPA)**.

Submit here your paper

Save the dates!

**Full paper  
submission deadline** April 13<sup>th</sup>, 2024

**Acceptance  
notification** June 1<sup>st</sup>, 2024

**Final paper  
submission** July 15<sup>th</sup>, 2024

### AWARDS

Don't miss the chance to win a prize.

- **1 Best Paper Award**
- **2 Best Student Paper Awards**

### TOPICS

- Susceptibility to EMI of analog and mixed signal IPs
- EMC of analog and digital sensors
- EMC of ICs for biomedical applications
- EMC of ICs for wireline communications
- Power electronics EMC/EMI
- EME of core blocks and I/Os
- EMC issues in SoC, SiP, and 3D ICs
- Substrate coupling in smart power ICs
- EMC-aware Design of ICs and Guidelines
- Tools to handle EMC at IC and module level
- SI and PI at IC and PCB level
- Measurement methods for chip level EMC
- EMC Standards and regulations
- Materials for improved EMC of ICs
- Long term electromagnetic robustness of ICs
- Influence of IC EMC on system design





## TUTORIALS AND SHORT COURSES

Tutorials and short courses will be organized as interactive educational presentations to provide up-to-date practical help to those new to the subject or requiring an update, as well as to address in-depth topical subjects. Tutorials and short courses are planned for the first day of the workshop, i.e., October 7<sup>th</sup>, 2024. For accepted proposals, the tutorial organizer will be responsible for soliciting presentations, corresponding with session speakers, corresponding with the Workshop Local Committee, and moderating the session at the workshop. Please, send the tutorial and short course proposals to [tpc.emccompo24@polito.it](mailto:tpc.emccompo24@polito.it) before June 6<sup>th</sup>, 2024.

## SPONSORSHIP

It is also possible to take advantage of many sponsorship opportunities. Proposals of Diamond Sponsor, Gold Sponsor and Silver Sponsor packages are available, but any form of sponsoring (technical, financial or any other) to promote the workshop is very welcome. To become a conference sponsor please write to [info.emccompo24@polito.it](mailto:info.emccompo24@polito.it).

## EXHIBITION

The Workshop will be accompanied by a technical exhibition on IC EMC and RF/microwave measurements and instrumentation. We also invite manufacturers and dealers of EMC-related equipment and tools, measurement and test equipment, spectrum monitoring and measurement systems, protecting device and components, microwave instrumentation, electromagnetic analysis and synthesis software.

The technical exhibition will be held from October 7<sup>th</sup>, 2024, to October 9<sup>th</sup>, 2024. The exhibition area is directly accessible from the conference rooms and ensure that delegates have the opportunity to visit it. An exhibition booth can be ordered. To exhibit, send the application before **July 30<sup>th</sup>, 2024** to [exhibits.emccompo24@polito.it](mailto:exhibits.emccompo24@polito.it). For more details please visit the conference website at the page [www.emccompo2024.it/for-exhibitors/](http://www.emccompo2024.it/for-exhibitors/).

## INFO FOR AUTHORS AND EXHIBITORS

<b>Paper submission starting</b>	Feb. 1 <sup>st</sup> , 2024
<b>Deadline for paper submission</b>	April 13 <sup>th</sup> , 2024
<b>Tutorial Proposal deadline</b>	June 6 <sup>th</sup> , 2024
<b>Notification of acceptance</b>	June 1 <sup>st</sup> , 2024
<b>Final paper submission</b>	July 15 <sup>th</sup> , 2024

## LOCAL ORGANIZING COMMITTEE

### General Chair

Franco Fiori Politecnico di Torino

### TPC Chair

Flavia Grassi Politecnico di Milano

### Members

Francesco De Paulis	Università dell'Aquila
Markeljan Fishta	Politecnico di Torino
Davide Pandini	STMicroelectronics
Erica Raviola	Politecnico di Torino
Anna Richelli	Università di Brescia
Xinglong Wu	Politecnico di Milano

## TECHNICAL PROGRAM COMMITTEE

A. Barić	University of Zagreb	Croatia
A. Boyer	LAAS-CNRS	France
A. Durier	Continental	France
B. Boesman	Melexis	Belgium
B. Deutschmann	Technical Univ. of Graz	Austria
B. Vrignon	NXP	France
B. Li	IME-CAS	China
B. Scully	NASA Johnson Space Center	USA
D. Pandini	ST Microelectronics	Italy
D. Pissoor	KU Leuven Bruges	Belgium
E. Raviola	Politecnico di Torino	Italy
E. Li	Zhejiang University	China
E. Sicard	INSA Toulouse	France
F. Vargas	PUCRS	Brazil
F. Fiori	Politecnico di Torino	Italy
F. Klotz	Infineon	Germany
F. Lafon	Valeo	France
H. Park	Samsung	South Korea
H. Poes	Melexis	Belgium
H. H. Park	University of Suwon	South Korea
J. Kruppa	Infineon	Germany
J. Niehof	NXP	Netherlands
J. M. Redoute	University of Liege	Belgium
J. Raoult	Montpellier University	France
J. Wu	NUDT	China
K. O' Leary	Mixed Signal Systems	UK
K. Abouda	NXP	France
M. Nagata	Kobe University	Japan
M. Coenen	EMCMCC	Netherlands
M. Yamaguchi	Tohoku University	Japan
M. Merlo	ST Microelectronics	Italy
M. Ramdani	ESEO Angers	France
M. Okushima	Renesas	Japan
O. Wada	Kyoto University	Japan
R. Serra	TU Eindhoven	Netherlands
R. Xian-Ke Gao	IHPC A*STAR	Singapore
R. Gillon	SYDELITY	Belgium
R. Perdriau	ESEO Angers	France
S. Ahn	KAIST	Korea
S. Miropolsky	Infineon	Germany
S. Yuan	Feng Chia University	Taiwan
S. Ben Dhia	LAAS-CNRS	France
U. Paoletti	Hitachi Ltd.	Japan
W. Wilkening	Bosch	Germany

## CONTACT INFORMATION

Info [info.emccompo24@polito.it](mailto:info.emccompo24@polito.it)

For tutorial [tpc.emccompo24@polito.it](mailto:tpc.emccompo24@polito.it)

For exhibitors [exhibits.emccompo24@polito.it](mailto:exhibits.emccompo24@polito.it)

